2SD1257, 2SD1257A

Silicon NPN epitaxial planar type

For power switching

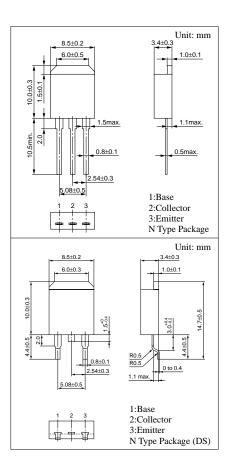
Complementary to 2SB0934 (2SB934)

Features

- Low collector to emitter saturation voltage V_{CE(sat)}
- Satisfactory linearity of foward current transfer ratio h_{FE}
- Large collector current I_C
- N type package enabling direct soldering of the radiating fin to the printed circuit board, etc. of small electronic equipment.

Parameter		Symbol	Ratings	Unit		
Collector to	2SD1257	N7	130	V		
base voltage	2SD1257A	V _{CBO}	150	V		
Collector to	2SD1257	V	80	V		
emitter voltage	2SD1257A	V _{CEO}	100	v		
Emitter to base voltage		V_{EBO}	7	V		
Peak collector current		I _{CP}	15	А		
Collector current		I _C	7	А		
Collector power T _C =25°C		D	40	117		
dissipation	Ta=25°C	P _C	1.3	W		
Junction temperature		Tj	150	°C		
Storage temperature		T _{stg}	-55 to +150	°C		

Absolute Maximum Ratings $(T_c=25^{\circ}C)$

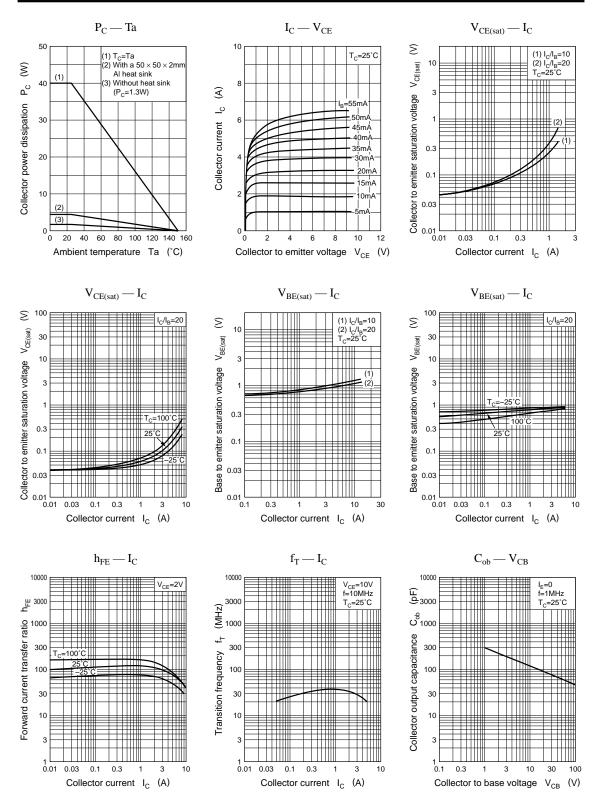


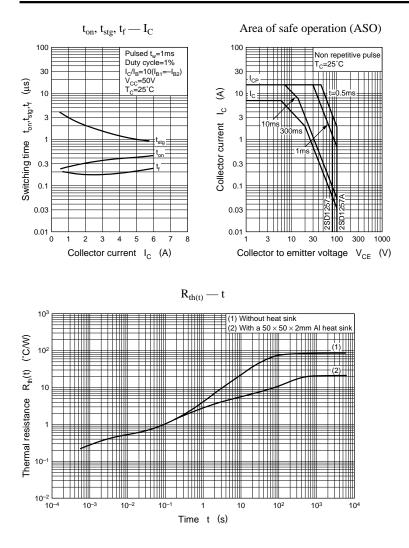
Electrical Characteristics $(T_C=25^{\circ}C)$

Parameter		Symbol	Conditions	min	typ	max	Unit
Collector cutoff current		I _{CBO}	$V_{CB} = 100V, I_E = 0$			10	μA
Emitter cutoff curren	t	I _{EBO}	$V_{EB} = 5V, I_{C} = 0$			50	μA
Collector to emitter	2SD1257	N		80			N
voltage	2SD1257A	V _{CEO}	$I_{\rm C} = 10 {\rm mA}, I_{\rm B} = 0$	100			V
Forward current transfer ratio		h _{FE1}	$V_{CE} = 2V, I_C = 0.1A$	45			
		h _{FE2} *	$V_{CE} = 2V, I_C = 3A$	60		260	
Collector to emitter saturation voltage		V _{CE(sat)}	$I_{\rm C} = 5A, I_{\rm B} = 0.25A$			0.5	v
Base to emitter saturation voltage		V _{BE(sat)}	$I_{\rm C} = 5A, I_{\rm B} = 0.25A$			1.5	v
Transition frequency		f _T	$V_{CE} = 10V, I_C = 0.5A, f = 10MHz$		30		MHz
Turn-on time		t _{on}			0.5		μs
Storage time		t _{stg}	$I_{\rm C} = 3A, I_{\rm B1} = 0.3A, I_{\rm B2} = -0.3A,$		1.5		μs
Fall time		t _f	$V_{CC} = 50V$		0.1		μs

*hFE2 Rank classification

Rank	R	Q	Р	
h _{FE2}	60 to 120	90 to 180	130 to 260	- - Note) The part numbers in the parenthesis show conventional part number





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